

10591645

SM 9/22

PATENT  
Attorney Docket No. 07553.0065  
Customer Number: 22,852

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the specification as follows:

Add the following new paragraph after the title at page 1:

**CROSS REFERENCE TO RELATED APPLICATIONS**

This application is a National Phase Application of International Application Number PCT/JP2005/003609, filed March 3, 2005, and claims the priority of Japanese Patent Application No. 2004-063228, filed March 5, 2004, the content of both of which is incorporated herein by reference.

Please amend the first full paragraph, at page 3, line 3 to page 4, line 1/2 as follows:

However, in recent years, in accordance with sophistication of functions and speed increase of an integrated circuit, a wiring structure has rapidly become more microscopic and thinner and a wiring layer has become extremely thin, and therefore, giving a stylus pressure to a the probe for the inspection as described in the conventional patent document 1 involves a risk of damaging a wiring layer and an insulation layer because the probe penetrates not only the oxide film but also the wiring layer or because of a concentration stress from the probe. On the contrary, decreasing the stylus pressure involves a risk of causing unstable continuity between a the probe and an the electrode pad. Further, though the bumps described in the patent documents 2, 3 can surely break an the oxide film of an electrode pad by the